



SOT-23-6L Plastic-Encapsulate MOSFETS

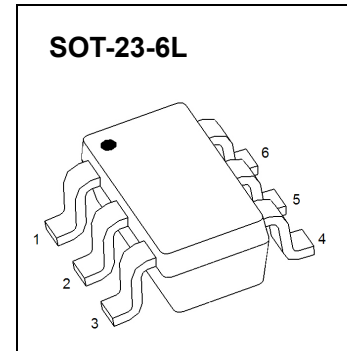
CJL6602A P-channel and N-channel Complementary MOSFETS

P-channel

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
-30V	79mΩ@-10V	-2.3A
	118mΩ@-4.5V	

N-channel

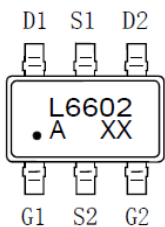
$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
30V	39mΩ@10V	3.4A
	56mΩ@4.5V	



GENERAL DESCRIPTION

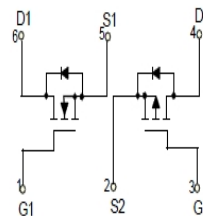
The CJL6602A uses advanced trench technology to provide excellent $R_{DS(on)}$ and low gate charge. The complementary MOSFETS form a high-speed power inverter and suitable for a multitude of applications.

MARKING



L6602A=Device code
 Solid point=Pin1 positioning point
 XX=Date Code

Equivalent Circuit



Maximum Ratings ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value		Unit
		N-channel	P-channel	
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 12	± 12	V
Continuous Drain Current ⁽¹⁾	I_D	3.4	-2.3	A
Pulsed Drain Current ⁽²⁾	I_{DM}	30	-30	A
Power Dissipation	P_D	0.83	0.83	W
Thermal Resistance from Junction to Ambient ⁽¹⁾	$R_{\theta JA}$	150	150	$^\circ\text{C}/\text{W}$
Operation Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	-55~+150	$^\circ\text{C}$

1.The value of $R_{\theta JA}$ is measured with the device one-side active only, mounted on 1 in² FR-4 board with 2oz. single-sided Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

2.Repetitive rating,pulse with limited by junction temperature.

MOSFET ELECTRICAL CHARACTERISTICS

N-channel MOSFET Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
Gate-source leakage current (note1)	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
Drain-source on-resistance (note1)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 3A$		30	39	m Ω
		$V_{GS} = 4.5V, I_D = 3A$		43	56	m Ω
Forward tranconductance (note1)	g_{FS}	$V_{DS} = 5V, I_D = 3A$	3			S
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.8	3.0	V
Diode forward voltage (note1)	V_{SD}	$I_S = 1A, V_{GS} = 0V$			1	V
Dynamic characteristics (note2)						
Input capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		302		pF
Output capacitance	C_{oss}			39		pF
Reverse transfer capacitance	C_{rss}			28		pF
Gate resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		6		Ω
Switching Characteristics (note2)						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 15V,$ $R_L = 5\Omega, R_{GEN} = 6\Omega$		0.8		ns
Turn-on rise time	t_r			2		ns
Turn-off delay time	$t_{d(off)}$			6.8		ns
Turn-off fall time	t_f			3		ns
Total gate charge	Q_g	$V_{GS} = 6V, V_{DD} = 10V, I_D = 2A$		4.3		nC
Gate-source charge	Q_{gs}			1.1		nC
Gate-drain charge	Q_{gd}			1.3		nC

- Notes :**
1. Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 0.5\%$.
 2. Guaranteed by design, not subject to production testing.

MOSFET ELECTRICAL CHARACTERISTICS

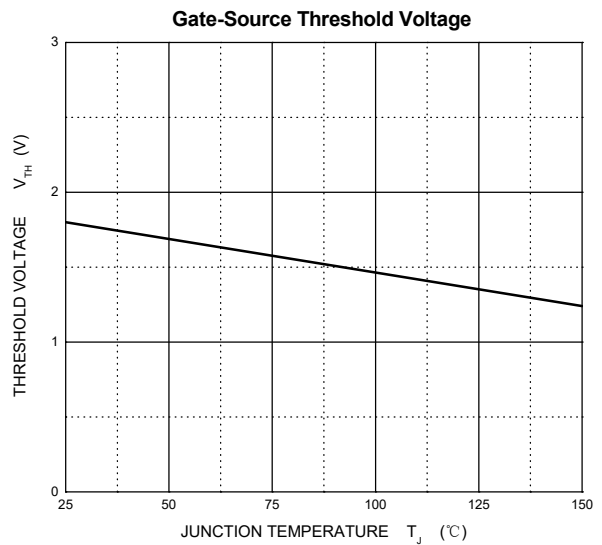
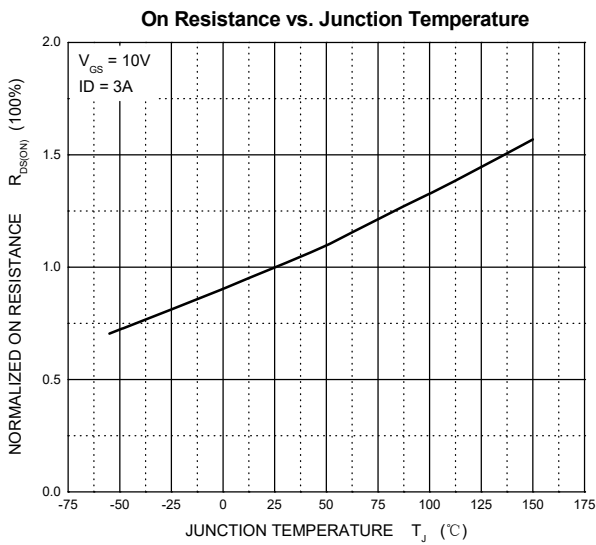
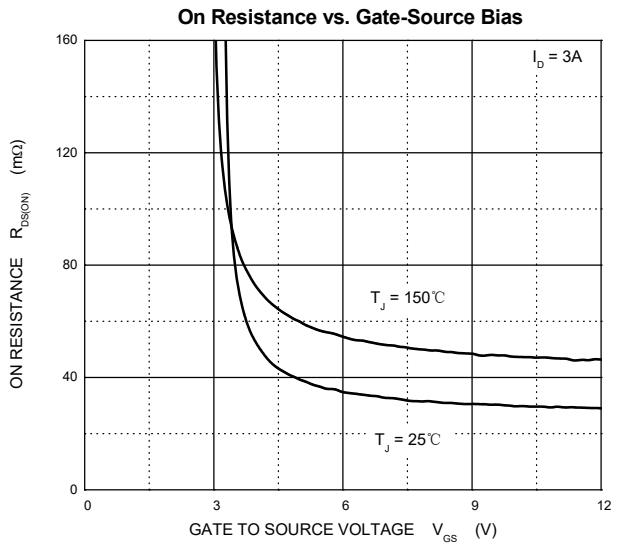
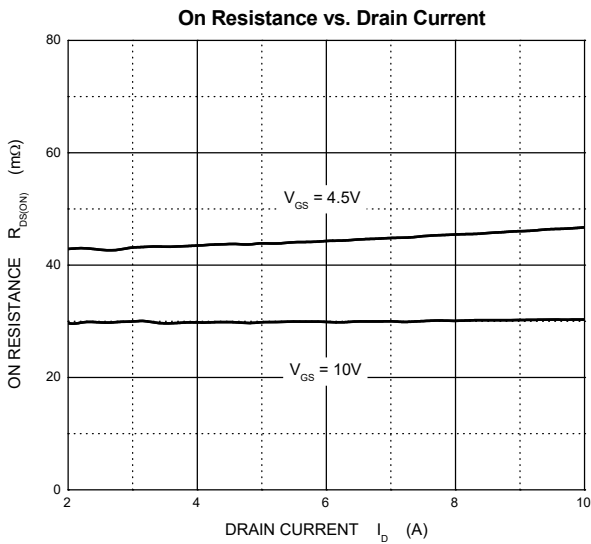
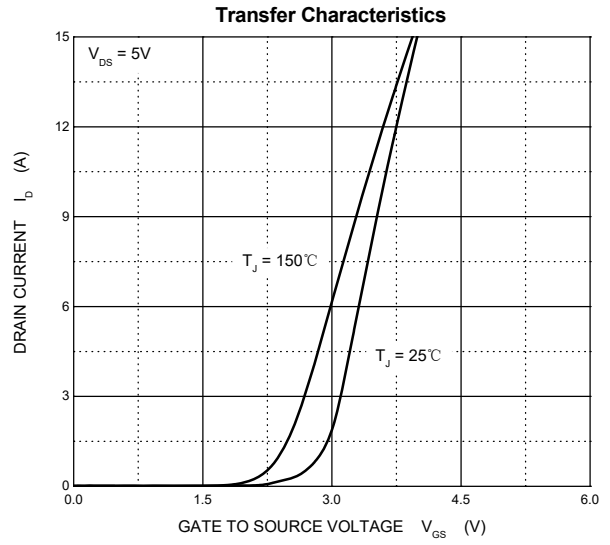
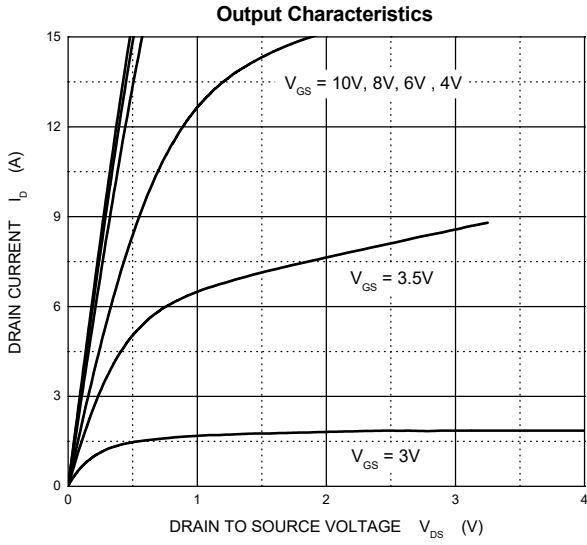
P-channel MOSFET Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -24V, V_{GS} = 0V$			-1	μA
Gate-source leakage current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
Drain-source on-resistance (note1)	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -2.3A$		61	79	m Ω
		$V_{GS} = -4.5V, I_D = -2A$		91	118	m Ω
Forward tranconductance (note1)	g_{FS}	$V_{DS} = -5V, I_D = -2.3A$	3			S
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-3.0	V
Diode forward voltage (note1)	V_{DS}	$I_S = -1A, V_{GS} = 0V$			-1	V
Dynamic characteristics (note2)						
Input capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$		291		pF
Output capacitance	C_{oss}			44		pF
Reverse transfer capacitance	C_{rss}			37		pF
Gate resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		10		Ω
Switching Characteristics (note2)						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -15V,$ $R_L = 6\Omega, R_{GEN} = 6\Omega$		13		ns
Turn-on rise time	t_r			10		ns
Turn-off delay time	$t_{d(off)}$			28		ns
Turn-off fall time	t_f			13		ns
Total gate charge	Q_g	$V_{GS} = -6V, V_{DD} = -10V, I_D = -2A$		4.5		nC
Gate-source charge	Q_{gs}			1		nC
Gate-drain charge	Q_{gd}			1.4		nC

- Notes :**
1. Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 0.5\%$.
 2. Guaranteed by design, not subject to production testing.

Typical Characteristics

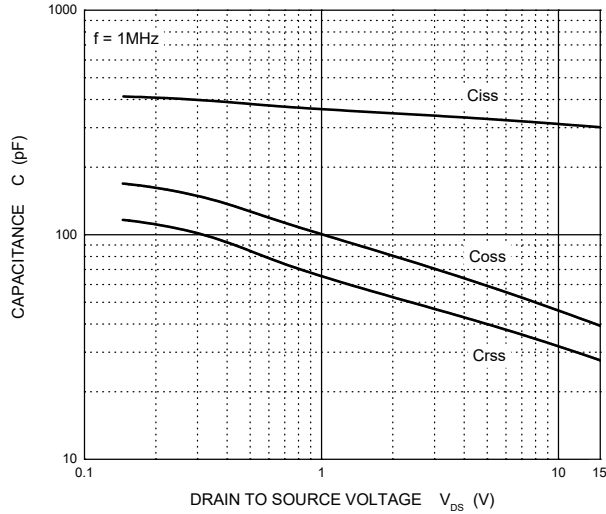
N-Channel-MOS



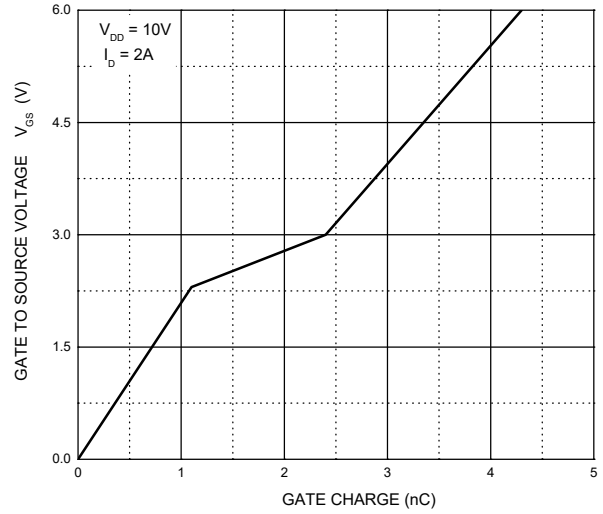
Typical Characteristics

N-Channel-MOS

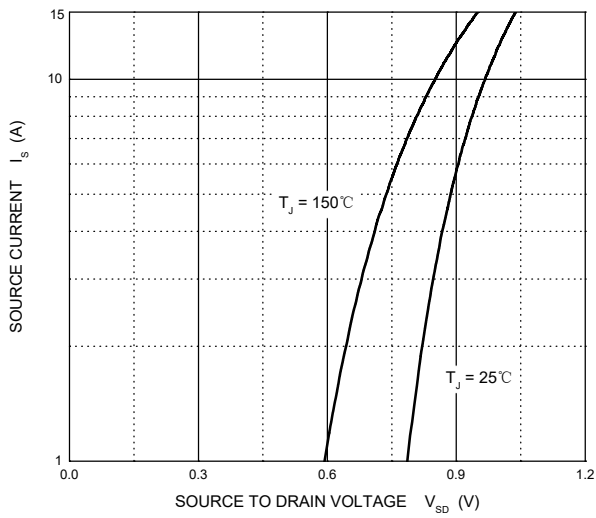
Typical Capacitances



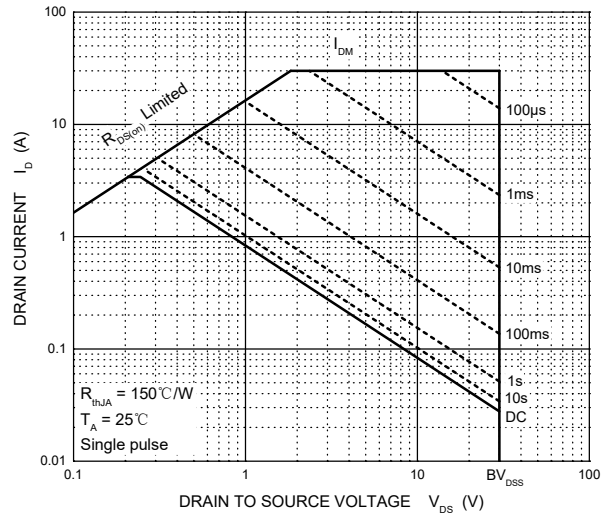
Gate Charge



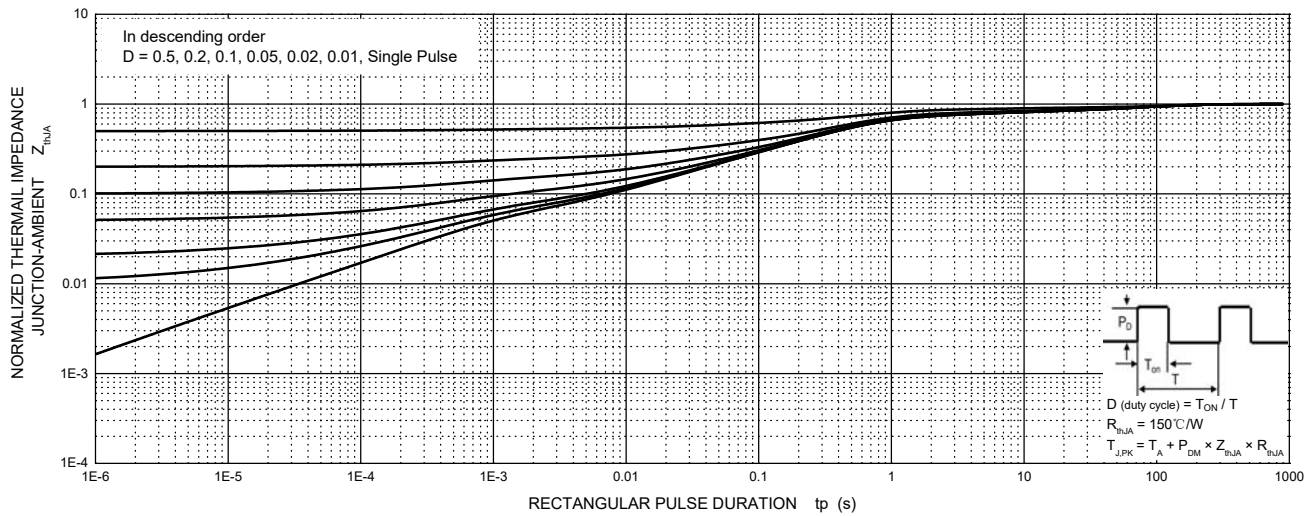
Source-Drain Diode Forward Characteristics



Maximum Safe Operating Area

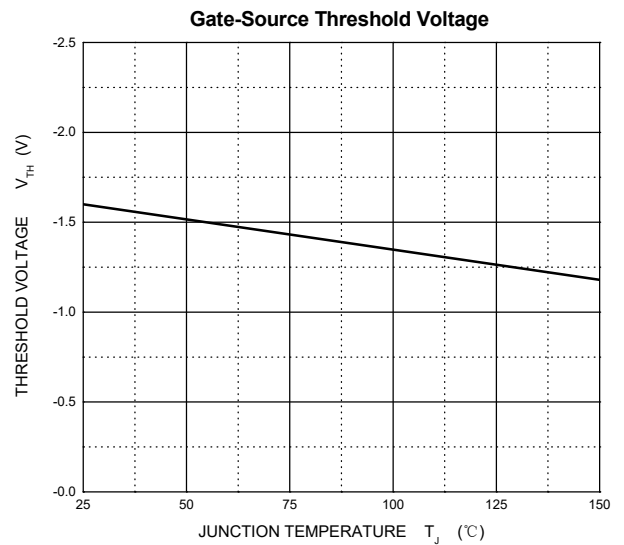
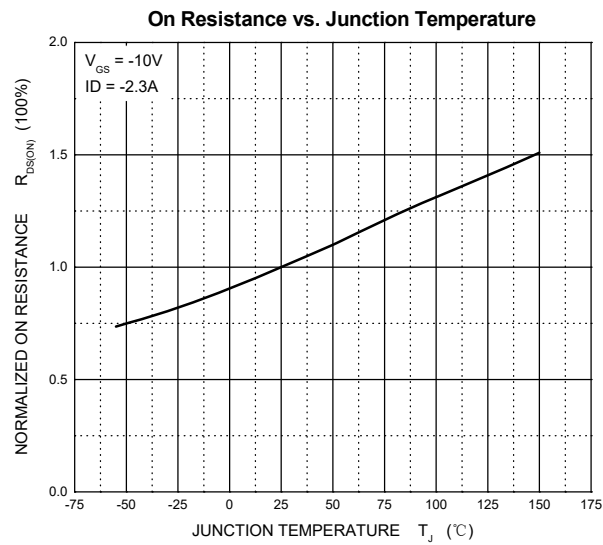
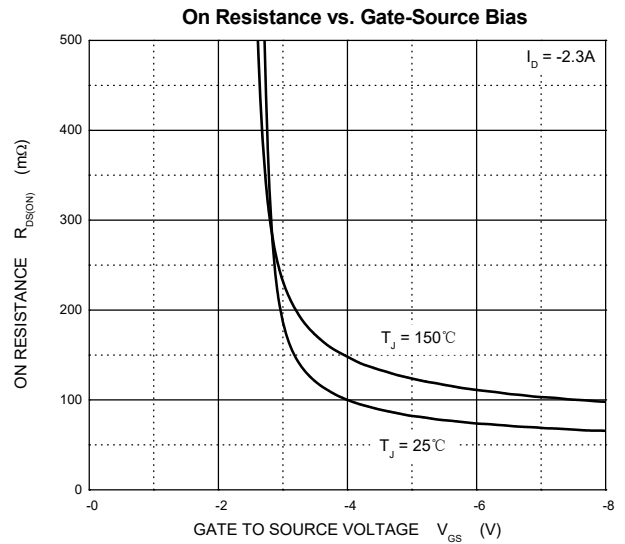
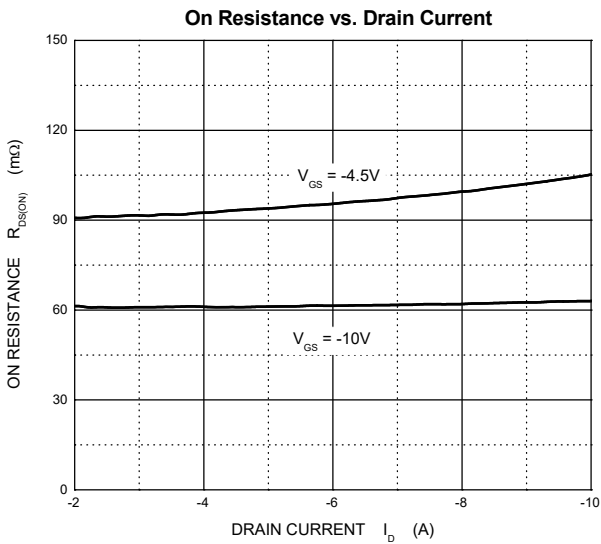
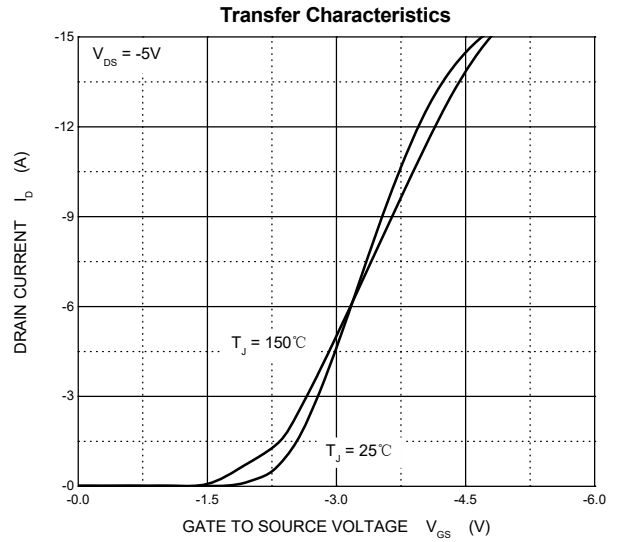
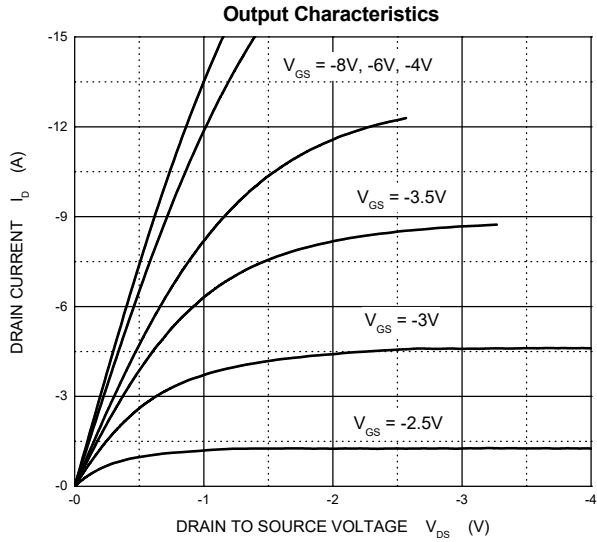


Transient Thermal Impedance, Junction-Case



Typical Characteristics

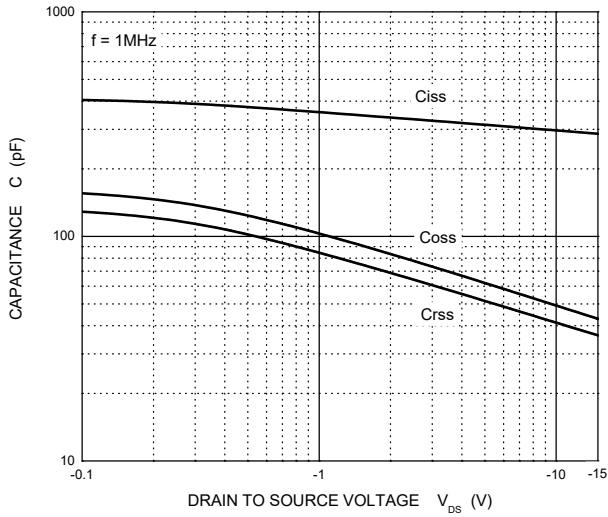
P-Channel-MOS



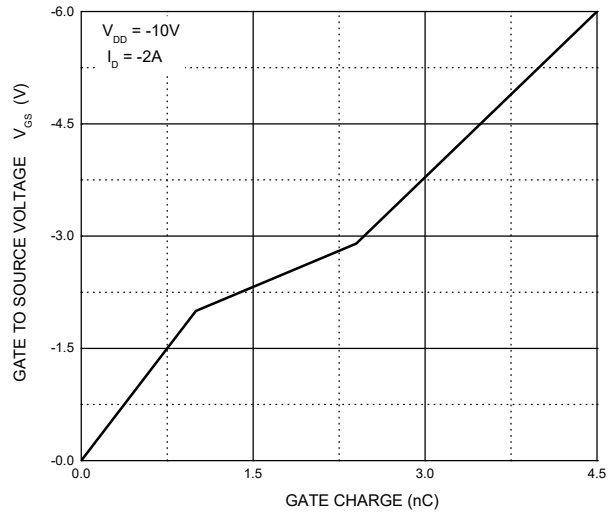
Typical Characteristics

P-Channel-MOS

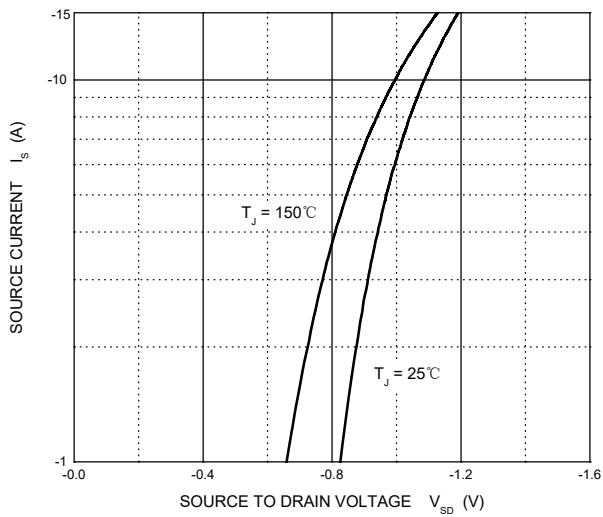
Typical Capacitances



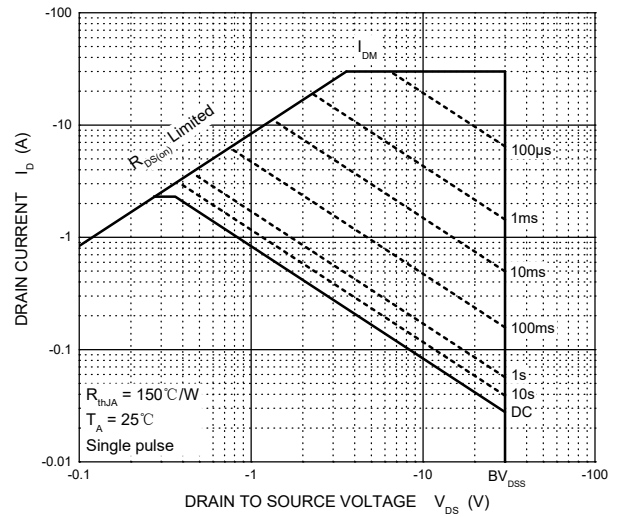
Gate Charge



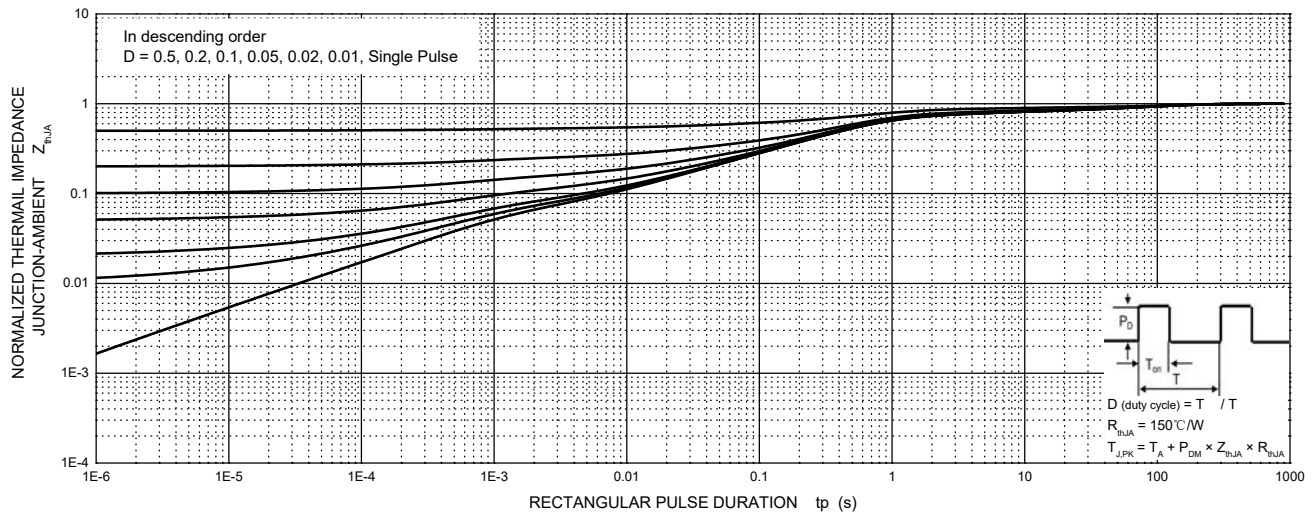
Source-Drain Diode Forward Characteristics



Maximum Safe Operating Area

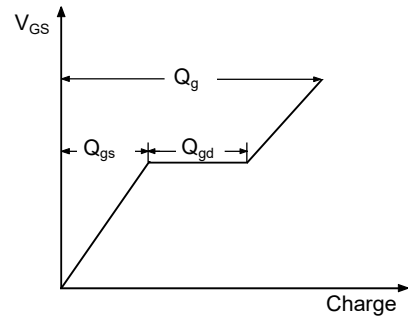
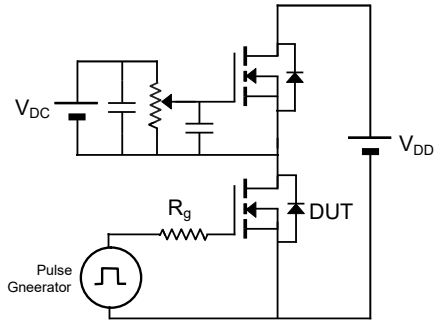


Transient Thermal Impedance, Junction-Case

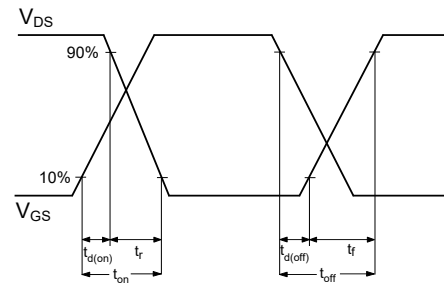
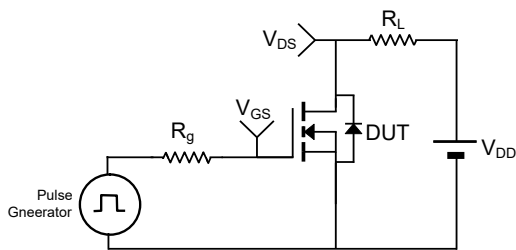


TEST CIRCUIT AND WAVEFORMS

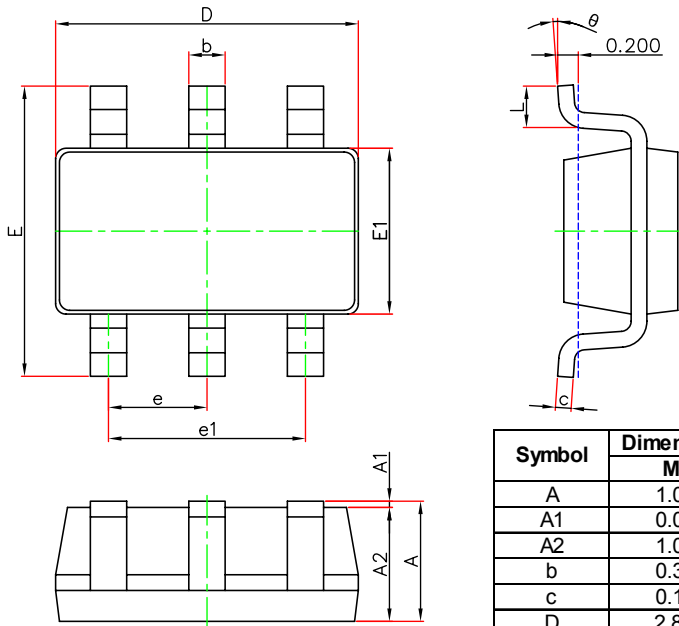
Gate Charge



Resistive Load Switching Time

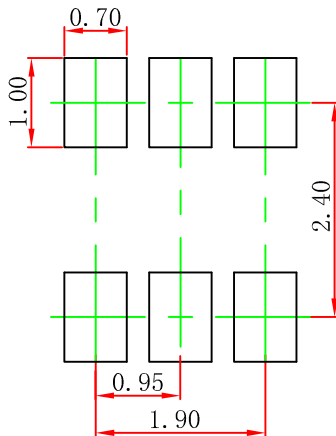


SOT-23-6L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

SOT-23-6L Suggested Pad Layout



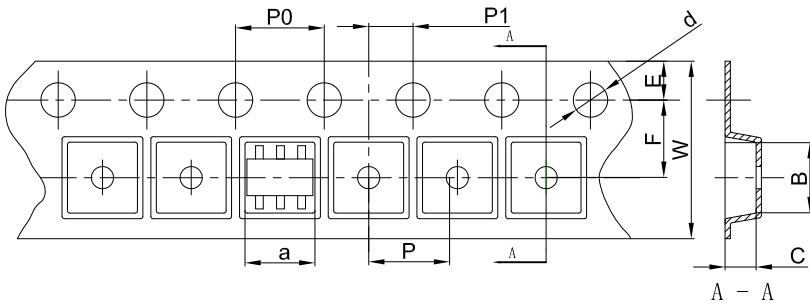
- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

NOTICE

JSCJ reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

SOT-23-6L Tape and Reel

SOT-23-6L Embossed Carrier Tape

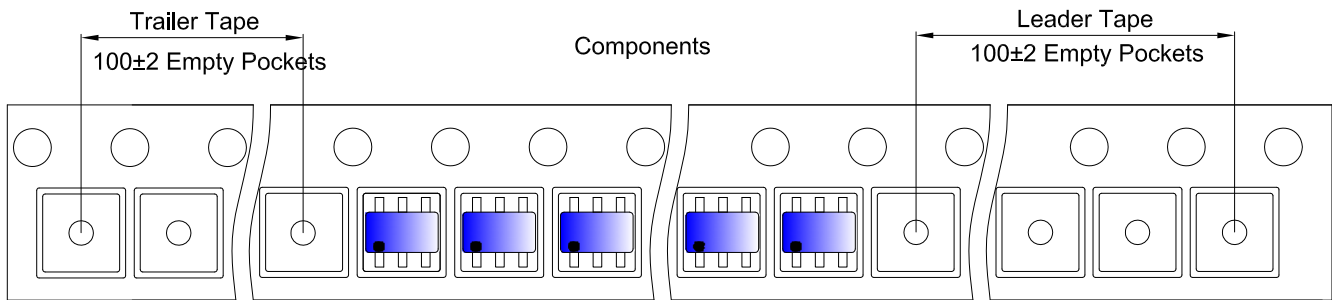


Packaging Description:

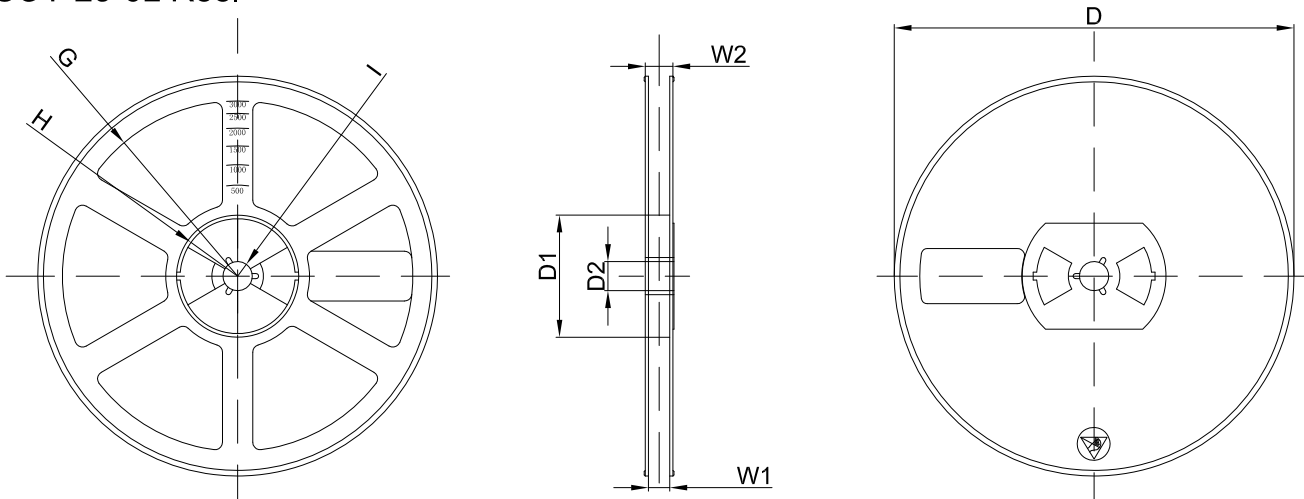
SOT-23-6L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 18.0cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
SOT-23-6L	3.23	3.17	1.37	Ø1.55	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23-6L Tape Leader and Trailer



SOT-23-6L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Ø180.00	60.00	13.00	R78.00	R25.60	R6.50	9.50	13.10

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	